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Total Number of Pages: 01

B.Tech BSCP1207

4th Semester Back Examination 2018-19 PHYSICS OF SEMICONDUCTOR DEVICES BRANCH: AEIE, CSE, ECE, EEE, EIE, ETC, IEE

Time: 3 Hours Max Marks: 70 Q.CODE: F645

Answer Question No.1 which is compulsory and any FIVE from the rest.

The figures in the right hand margin indicate marks.

Q1	a) b) c) d) e) f) g) h) i)	Answer the following questions: What do you mean by effective mass of electron? Define acceptor density and donor density? Graphically show the variation of carrier concentration with temperature. Define drift current and diffusion current. Write down the Einstein Relation? What do you mean by depletion layer and potential barrier? What is early voltage and punch through voltage? Compare the Schottky barrier and pn junction. What do you mean by accumulation charge? Distinguish between n-channel and p-channel MOSFET structure.	(2 x 10)		
Q2	a) b)	Discuss the splitting of energy levels with reference to silicon atom. What is band theory of solids? Give the energy band structure of insulators, semiconductors and conductors.	(5) (5)		
Q3 a) b)	a)	1			
	b)	temperature variation using suitable diagram and plot. Derive an expression for drift current.			
Q4 a) b)		Derive an expression for the current density as a function of applied voltage in a pn junction			
		Derive an expression for minority carrier concentration for hole in emitter region and hence find the expression for base current.			
Q5 a) b)	a)	, , , , , , , , , , , , , , , , , , , ,			
	b)	related to position of maximum barrier height due to Schottky effect. Derive expression for that flat band voltage of a MOS capacitor with p-type semiconductor substrate.			
Q6		Derive equation for electrons, holes and $n_{_0}p_{_0}$ product, when the semiconductor is in equilibrium condition.	(10)		
Q7		What is junction breakdown? Discuss different breakdown that is associated with a PN junction.	(10)		
Q8	a) b)	Write short answer on any TWO : Direct and indirect band gap semiconductor Ebers-Moll model	(5 x 2)		

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